MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

LFPAK8 4.90x4.80x1.12MM, 1.27P
CASE 760AA
ISSUE D
DATE 22 APR 2024

NOTES:
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.150mm PER SIDE.
4. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
5. OPTIONAL MOLD FEATURE.

**FOR ADDITIONAL INFORMATION ON OUR PB−FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.**

**GENERIC MARKING DIAGRAM**

XXXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
Y = Year
W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Some products may not follow the Generic Marking.

**DOCUMENT NUMBER:** 98AON82475G
**DESCRIPTION:** LFPAK8 4.90x4.80x1.12MM, 1.27P

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